

OP07 Die Revision, Wafer Fabrication Site & Process Change

Qualification Results Summary of OP07 Die Revision, Wafer Fabrication Site & Process Change

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Early Life Failure Rate (ELFR)	MIL-STD-883, M1015	4 x 500	Pass
High Temperature Operating Life (HTOL)	JEDEC <i>JESD22-A108</i>	3 x 77	Pass
Highly Accelerated Stress Test (HAST) ¹	JEDEC <i>JESD22-A110</i>	3 x 77	Pass
Solder Heat Resistance (SHR) ¹	JEDEC <i>J-STD-020</i>	1 x 30	Pass
Temperature Cycle (TC) ¹	JEDEC <i>JESD22-A104</i>	1 x 77	Pass
Unbiased Highly Accelerated Stress Test (UHAST) ¹	JEDEC <i>JESD22-A118</i>	1 x 77	Pass
Latch-Up	JEDEC <i>JESD78</i>	3/test	Pass ±200 mA, ±22.5 V
Electrostatic Discharge <i>Human Body Model</i> ²	ESDA/JEDEC <i>JS-001-2011</i>	3/voltage	Pass ±2000 V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-A114</i>	3/voltage	Pass ±1250 V

¹ Preconditioned per JEDEC J-STD-020 Level 1

² HBM testing shows the OP07 passes at all level between 750 V and 2 kV, but failures occur at 500 V.